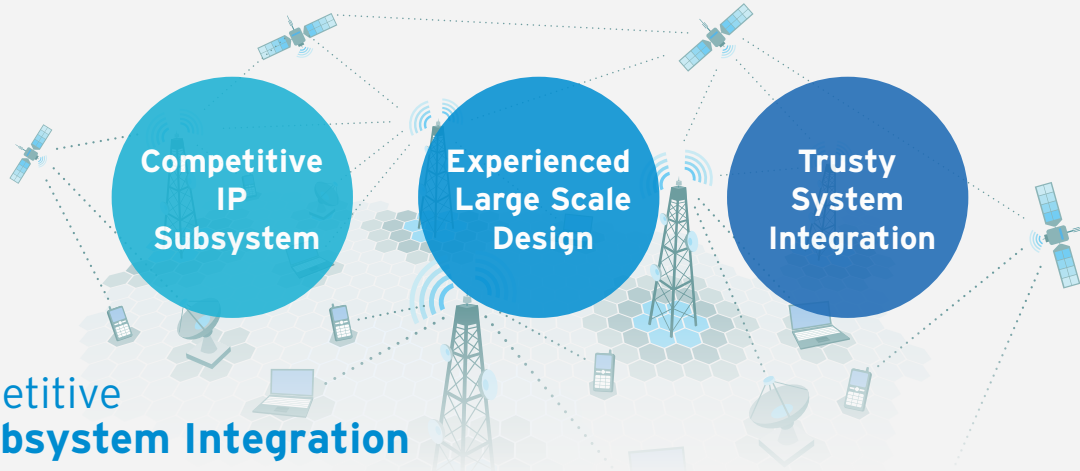


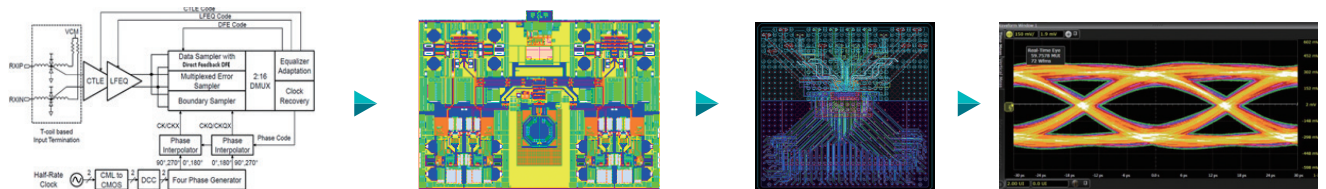
# Turnkey Solution for Networking



## Competitive IP Subsystem Integration

- 28G/56G/112G SerDes
- Multiple protocol support (PCIe, GbE, JESD204B/C, CPRI...)
- GUC multi-die interLink (GLink) for chiplet and SiP applications
- Rich memories portfolio (HBM, TCAM, Customized SRAM..., etc)
- High Speed ADC/DAC for 5G

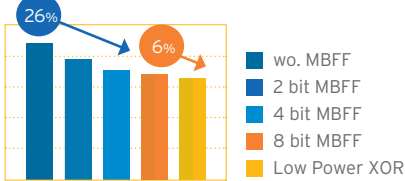
### SerDes



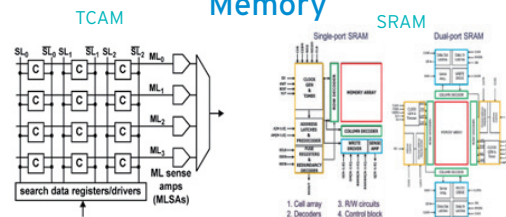
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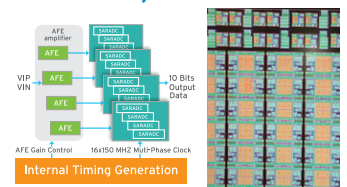
### Customized Cell



### Memory



### Gbps AFE



### Home / Datacenter Network

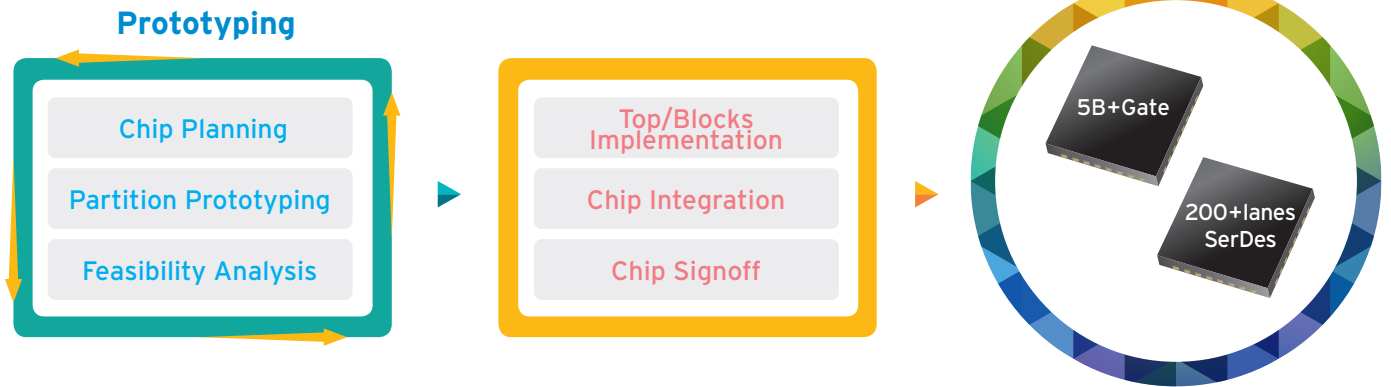


### Telecomm



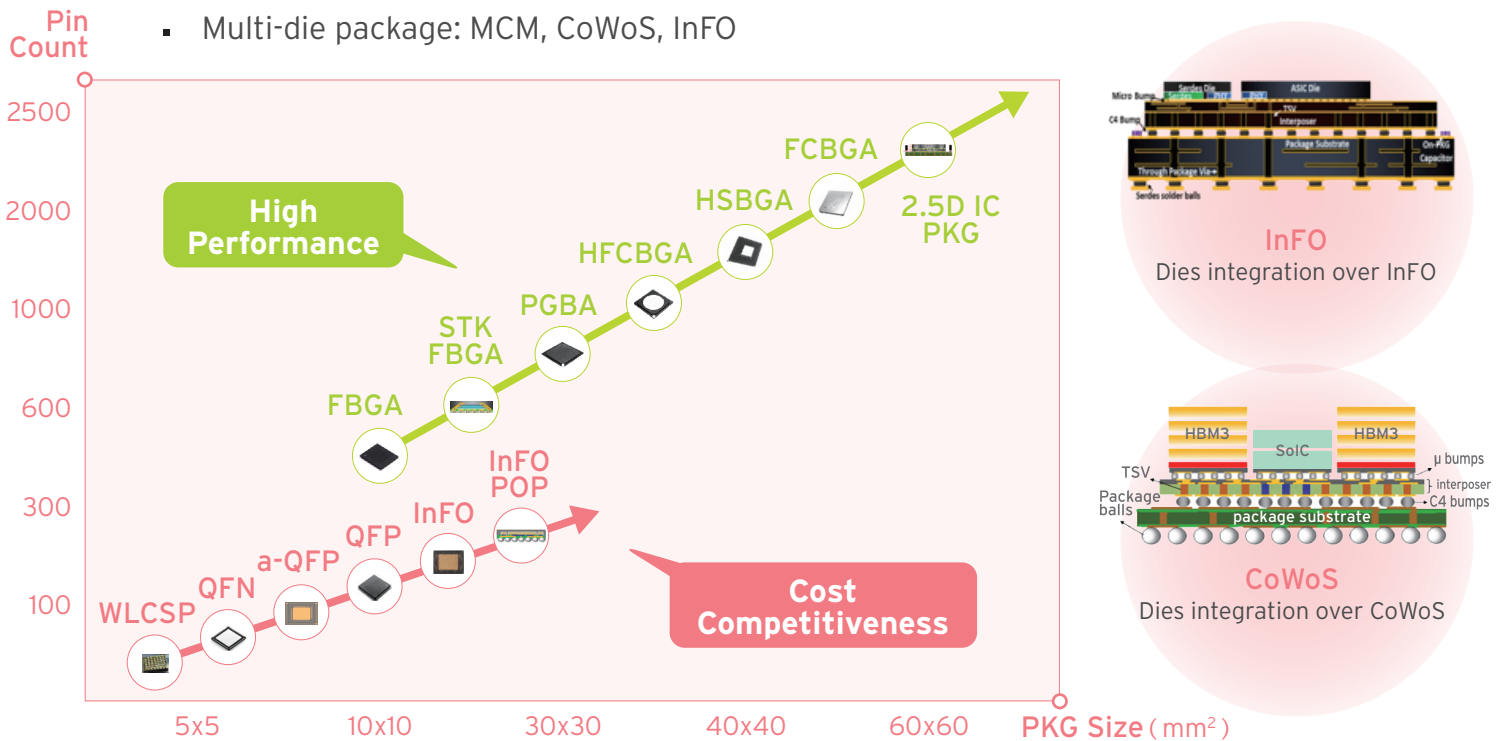
## Experienced Large Scale Design

- Advance process: 7nm/6nm/5nm/3nm
- 5B+gate count design
- 200+lanes 112G SerDes integration
- Hierarchical CTS planning
- Macro placement and BIST grouping



## Trusty System Integration

- Completed channel co-simulation (IP ▶ Package ▶ PCB)
- Multi-die package: MCM, CoWoS, InFO
- Comprehensive package service
- Guidance of PCB layout



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